

### FEATURES

- USB-PD Support
- Passes USB-IF Certification: Test ID 1010060
- 40V Input Voltage Surge
- 4.5V-36V Operational Input Voltage
- 5.1V/9.1V/12.1V Output with +/-1% Accuracy
- Up to 3.0A Output current
- Constant Current Regulation Limit
- Hiccup Mode Protection at Output Short
- >90% Efficiency at Full Load
- 0.5mA Low Standby Input Current
- 5.1V/9.1V/12.1V Output Over-Voltage Protection
- Cord Voltage Compensation
- Meet EN55022 Class B Radiated EMI Standard
- SOP-8EP Package

### APPLICATIONS

- Car Charger
- Cigarette Lighter Adaptor (CLA)
- Rechargeable Portable Device
- CV/CC regulation DC/DC converter

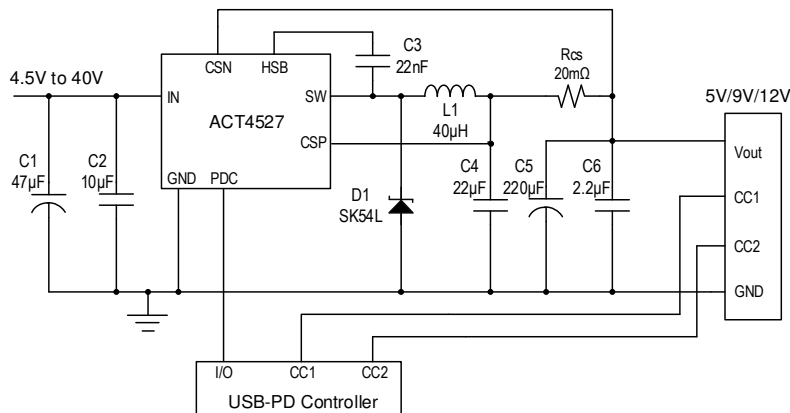
### GENERAL DESCRIPTION

ACT4527 is a wide input voltage, high efficiency step-down DC/DC converter that operates in either CV (Constant Output Voltage) mode or CC (Constant Output Current) mode. ACT4527 has an interface for USB-PD control via a tri-state digital pin. Vout is 5.1V if this pin is floating, Vout is 9.1V when this pin voltage is less than 0.8V and Vout is 12.1V while this pin voltage is more than 2.0V.

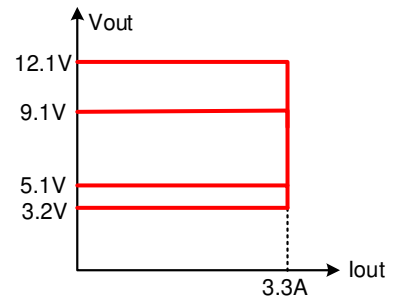
ACT4527 has accurate output current limits under constant current regulation. It provides up to 3.0A output current at 125kHz switching frequency. ACT4527 utilizes adaptive drive technique to achieve good EMI performance while main >90% efficiency at full load for mini size CLA designs. It also has output short circuit protection with hiccup mode. The average output current is reduced to below 6mA when output is shorted to ground. Other features include output over voltage protection and thermal shutdown.

This device is available in a SOP-8EP package and require very few external components for operation.

### TYPICAL APPLICATION CIRCUIT



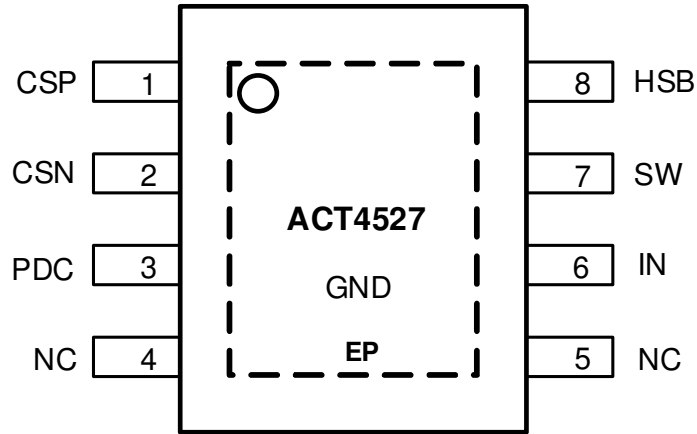
### V/I PROFILE



**ORDERING INFORMATION**

| PART NUMBER | OPERATION TEMPERATURE RANGE | PACKAGE | FREQUENCY | PACKING     |
|-------------|-----------------------------|---------|-----------|-------------|
| ACT4527YH-T | -40°C to 85°C               | SOP-8EP | 125kHz    | TAPE & REEL |

**PIN CONFIGURATION**



**SOP-8EP**

Top View

## PIN DESCRIPTIONS

| PIN | NAME | DESCRIPTION  |
|-----|------|--|
| 1   | CSP  | Voltage Feedback Input. Connect to node of the inductor and output capacitor. CSP and CSN Kelvin sense is recommended.                 |
| 2   | CSN  | Negative input terminal of output current sense. Connect to the negative terminal of current sense resistor                            |
| 3   | PDC  | USB-PD Control Pin. floating: 5.1V, pulled high: 12.1V, pulled low: 9.1V. Do not drive this pin higher than 5V.                        |
| 4   | NC   | No Connection Pin. Must leave this pin floating.   |
| 5   | NC   | No Connection Pin. Must leave this pin floating.   |
| 6   | IN   | Power Supply Input. Bypass this pin with a 10 $\mu$ F ceramic capacitor to GND, placed as close to the IC as possible.                 |
| 7   | SW   | Power Switching Output to External Inductor.   |
| 8   | HSB  | High Side Bias Pin. This provides power to the internal high-side MOSFET gate driver. Connect a 22nF capacitor from HSB pin to SW pin. |
| 9   | GND  | Ground and Heat Dissipation Pad. Connect this exposed pad to large ground copper area with copper and vias.                            |

## ABSOLUTE MAXIMUM RATINGS<sup>Ⓢ</sup>

| PARAMETER                              | VALUE                          | UNIT           |
|--|--------------------------------|----------------|
| IN to GND                              | -0.3 to 40                     | V              |
| SW to GND                              | -1 to $V_{IN} + 1$             | V              |
| HSB to GND                             | $V_{SW} - 0.3$ to $V_{SW} + 7$ | V              |
| CSP, CSN to GND                        | -0.3 to +15                    | V              |
| PDC to GND                             | -0.3 to +6                     | V              |
| All other pins to GND                  | -0.3 to +6                     | V              |
| Junction to Ambient Thermal Resistance | 46                             | $^{\circ}$ C/W |
| Operating Junction Temperature         | -40 to 150                     | $^{\circ}$ C   |
| Storage Junction Temperature           | -55 to 150                     | $^{\circ}$ C   |
| Lead Temperature (Soldering 10 sec.)   | 300                            | $^{\circ}$ C   |

<sup>Ⓢ</sup>: Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS

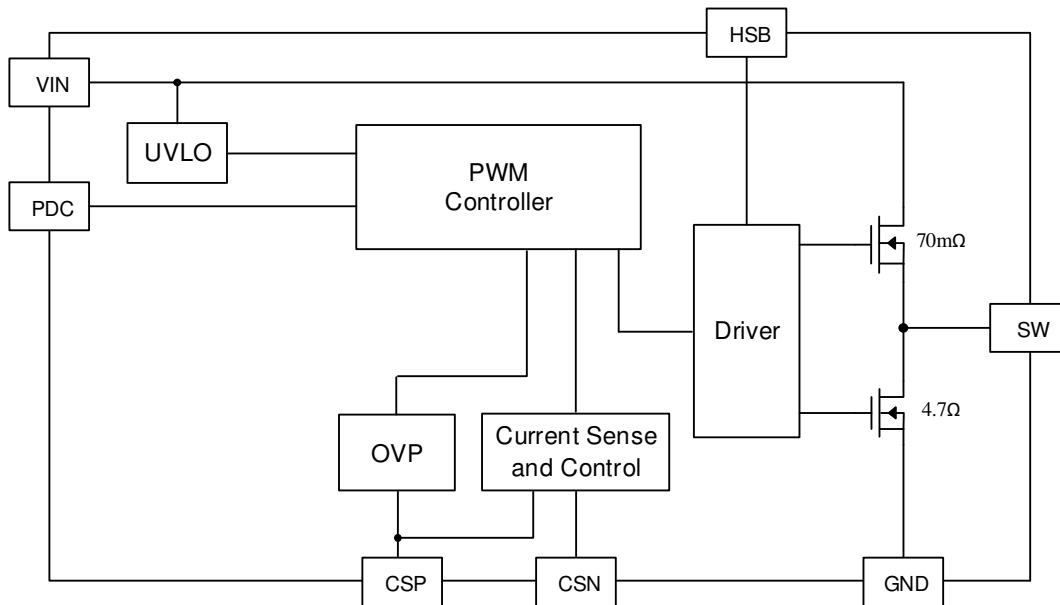
( $V_{IN} = 12V$ ,  $T_A = 25^\circ C$ , unless otherwise specified.)

| PARAMETER                              | SYMBOL    | TEST CONDITIONS             | MIN                  | TYP                 | MAX                  | UNIT |
|--|-----------|-----------------------------|----------------------|---------------------|----------------------|------|
| Input Over Voltage Protection          | VIN_OVP   | Rising                      | 40                   | 42                  | 44                   | V    |
| Input Over Voltage Hysteresis          |           |                             |                      | 4                   |                      | V    |
| Input Over Voltage Response Time       | T_VIN_OVP | VIN step from 30V to 45V    |                      | 250                 |                      | ns   |
| Input Under Voltage Lockout (UVLO)     | VIN       | Rising                      |                      | 4.5                 |                      | V    |
| Input UVLO Hysteresis                  |           |                             |                      | 200                 |                      | mV   |
| Input Voltage Power Good Deglitch Time |           | No OVP                      |                      | 40                  |                      | ms   |
|  |           | No UVP                      |                      | 10                  |                      | us   |
| Input Standby Current                  |           | Vin=12V, Vout=5.1V, Iload=0 |                      | 500                 |                      | uA   |
| Output Voltage Regulation              | CSP       |                             | 5.05<br>9.0<br>11.95 | 5.1<br>9.1<br>12.1  | 5.15<br>9.2<br>12.25 | V    |
| Output Over Voltage Protection (OVP)   |           | Output rising               |                      | 5.7<br>10.1<br>13.5 |                      | V    |
| Output Over Voltage Deglitch Time      |           |                             |                      | 1.0                 |                      | us   |
| Output Voltage Cord Compensation       |           | 66 mV between CSP and CSN   | -15%                 | 200                 | +15%                 | mV   |
| Output Under Voltage Protection (UVP)  | VOUT      | VOUT falling                | -10%                 | 3.2                 | 10%                  | V    |
| UVP Hysteresis                         | VOUT      | VOUT rising                 |                      | 0.2                 |                      | V    |
| UVP Deglitch Time                      | VOUT      |                             |                      | 10                  |                      | us   |
| UVP Blanking Time at Startup           |           |                             |                      | 3.5                 |                      | ms   |
| Output Constant Current Limit          |           | Rcs=20mΩ                    | 3.1                  | 3.3                 | 3.5                  | A    |
| Hiccup Waiting Time                    |           |                             |                      | 4.13                |                      | S    |
| Top FET Cycle by Cycle Current Limit   |           |                             | 4.5                  | 5.8                 |                      | A    |
| Top FET Rdson                          |           |                             |                      | 70                  |                      | mΩ   |
| Bottom FET Rdson                       |           |                             |                      | 4.7                 |                      | Ω    |
| Maximum Duty Cycle                     |           |                             | 99                   |                     |                      | %    |
| Switching Frequency                    |           |                             | -10%                 | 125                 | +10%                 | kHz  |
| Soft-Start Time                        |           |                             |                      | 2.0                 |                      | ms   |

## ELECTRICAL CHARACTERISTICS

( $V_{IN} = 12V$ ,  $T_A = 25^\circ C$ , unless otherwise specified.)

| PARAMETER                    | SYMBOL        | TEST CONDITIONS   | MIN  | TYP  | MAX  | UNIT       |
|------------------------------|---------------|---|------|------|------|------------|
| Out Voltage Ripples          |               | $C_{out}=220\mu F/22\mu F$ ceramic  |      | 80   |      | mV         |
| VOUT Discharge Current       |               | For high to lower voltage transitions   |      | 60   |      | mA         |
| Voltage transition time      |               | 12V-5V  |      |      | 100  | ms         |
|                              |               | 5V-12V  |      |      | 100  | ms         |
| Line Transient Response      |               | Input 12V-40V-12V with 1V/us slew rate, $V_{out}=5V$ , $I_{load}=0A$ and 2.4A | 4.75 |      | 5.25 | V          |
| Load Transient Response      | $V_{out}=5V$  | 80mA-1.0A-80mA load with 0.1A/us slew rate                                    | 4.9  | 5.15 | 5.4  | V          |
|                              | $V_{out}=9V$  | 80mA-1.0A-80mA load with 0.1A/us slew rate                                    | 8.7  | 9.1  | 9.5  | V          |
|                              | $V_{out}=12V$ | 80mA-1.0A-80mA load with 0.1A/us slew rate                                    | 11.6 | 12.1 | 12.6 | V          |
| Thermal Shut Down            |               |   |      | 160  |      | $^\circ C$ |
| Thermal Shut Down Hysteresis |               |   |      | 30   |      | $^\circ C$ |
| PDC Floating                 |               |   |      | 1.5  |      | V          |
| PDC High                     |               |   | 2.0  |      |      | V          |
| PDC Low                      |               |   |      |      | 0.8  | V          |
| PDC Maximum Voltage          |               |   |      |      | 5.5  | V          |
| PDC Drive Current            |               |   |      | 10   |      | $\mu A$    |

**FUNCTIONAL BLOCK DIAGRAM**

**FUNCTIONAL DESCRIPTION**
**Output Current Sensing and Regulation**

Sense resistor is connected to CSP and CSN. The sensed differential voltage is compared with interval reference to regulate current. CC loop and CV loop are in parallel. The current loop response is allowed to have slower response compared to voltage loop. However, during current transient response, the inductor current overshoot/undershoot should be controlled within +/-25% to avoid inductor saturation.

**Cycle-by-Cycle Current Control**

The conventional cycle-by-cycle peak current mode is implemented with high-side FET current sense.

**Input Over Voltage Protection**

The converter is disabled if the input voltage is above 42V (+/-2V). Device resumes operation automatically 40ms after OVP is cleared.

**Output Over Voltage Protection**

Device stops switching when output over-voltage is sensed, and resumes operation automatically when output voltage drops to OVP - hysteresis.

**Output Over Voltage Discharge**

Discharge circuit starts to discharge output through CSP pins when output over voltage is detected. Discharge circuit brings 12V down to 5V in less than 100ms.

**Output Under-Voltage Protection / Hiccup Mode**

There is a under voltage protection (UVP) threshold. If the UVP threshold is hit for 10us, an over current or short circuit is assumed, and the converter goes into hiccup mode by disabling the converter and restarts after hiccup waiting period.

**Cord Compensation**

In some applications, the output voltage is increased with output current to compensate the potential voltage drop across output cable. The compensation is based on the high side feedback resistance.

The compensation voltage is derived as:

$$\Delta V_{out} = (V_{CSP} - V_{CSN}) * K$$

Where  $K=3.03$

This voltage difference could be added on the reference or turning the  $(V_{CSP} - V_{CSN})$  voltage into a sink current at FB pin to pull  $V_{out}$  higher than programmed voltage.

The cord compensation loop should be very slow to avoid potential disturbance to the voltage loop. The

voltage loop should be sufficiently stable on various cord compensation setting.

### Thermal Shutdown

If the  $T_J$  increases beyond 160°C, ACT4527 goes into HZ mode and the timer is preserved until  $T_J$  drops by 30°C.

## APPLICATIONS INFORMATION

### Inductor Selection

The inductor maintains a continuous current to the output load. This inductor current has a ripple that is dependent on the inductance value.

Higher inductance reduces the peak-to-peak ripple current. The trade off for high inductance value is the increase in inductor core size and series resistance, and the reduction in current handling capability. In general, select an inductance value  $L$  based on ripple current requirement:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} f_{SW} I_{LOADMAX} K_{RIPPLE}} \quad (1)$$

Where  $V_{IN}$  is the input voltage,  $V_{OUT}$  is the output voltage,  $f_{SW}$  is the switching frequency,  $I_{LOADMAX}$  is the maximum load current, and  $K_{RIPPLE}$  is the ripple factor. Typically, choose  $K_{RIPPLE} = 30\%$  to correspond to the peak-to-peak ripple current being 30% of the maximum load current.

With a selected inductor value the peak-to-peak inductor current is estimated as:

$$I_{LPK-PK} = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{L \times V_{IN} \times f_{SW}} \quad (2)$$

The peak inductor current is estimated as:

$$I_{LPK} = I_{LOADMAX} + \frac{1}{2} I_{LPK-PK} \quad (3)$$

The selected inductor should not saturate at  $I_{LPK}$ . The maximum output current is calculated as:

$$I_{OUTMAX} = I_{LIM} - \frac{1}{2} I_{LPK-PK} \quad (4)$$

$I_{LIM}$  is the internal current limit.

### Input Capacitor

The input capacitor needs to be carefully selected to maintain sufficiently low ripple at the supply input of the converter. A low ESR capacitor is highly recommended. Since large current flows in and out of this capacitor during switching, its ESR also affects efficiency.

The input capacitance needs to be higher than 10 $\mu$ F. The best choice is the ceramic type. However, low ESR tantalum or electrolytic types may also be used provided that the RMS ripple current rating is higher than 50% of the output current. The input capacitor should be placed close to the IN and GND pins of the IC, with the shortest traces possible. In the case of tantalum or electrolytic types, a ceramic capacitor is recommended to parallel with tantalum or electrolytic capacitor, which should be placed right next to the IC.

### Output Capacitor

The output capacitor also needs to have low ESR to keep low output voltage ripple. The output ripple voltage is:

$$V_{RIPPLE} = I_{LPK-PK} \left( R_{ESR} + \frac{1}{8 \times f_{SW} \times C_{OUT}} \right) \quad (5)$$

Where  $I_{OUTMAX}$  is the maximum output current,  $K_{RIPPLE}$  is the ripple factor,  $R_{ESR}$  is the ESR of the output capacitor,  $f_{SW}$  is the switching frequency,  $L$  is the inductor value, and  $C_{OUT}$  is the output capacitance. In the case of ceramic output capacitors,  $R_{ESR}$  is very small and does not contribute to the ripple. Therefore, a lower capacitance value can be used for ceramic type. In the case of tantalum or electrolytic capacitors, the ripple is dominated by  $R_{ESR}$  multiplied by the ripple current. In that case, the output capacitor is chosen to have sufficiently low ESR.

For ceramic output capacitor, typically choose a capacitance of about 22 $\mu$ F. For tantalum or electrolytic capacitors, choose a capacitor with less than 50m $\Omega$  ESR. If an 330 $\mu$ F or 470 $\mu$ F electrolytic capacitor is used, where ripple is dominantly caused by ESR, an 2.2 $\mu$ F ceramic is recommended.

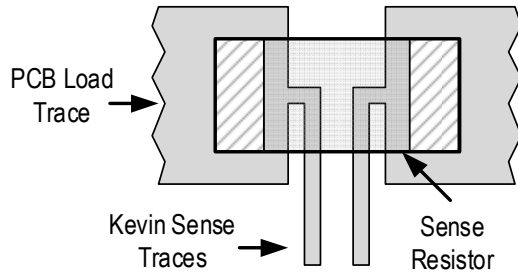
### Rectifier Schottky Diode

Use a Schottky diode as the rectifier to conduct current when the High-Side Power Switch is off. The Schottky diode must have current rating higher than the maximum output current and a reverse voltage rating higher than the maximum input voltage. Further more, the low forward voltage Schottky is preferable for high efficiency and smoothly operation.

### Current Sense Resistor

The traces leading to and from the sense resistor can be significant error sources. With small value sense resistors, trace resistance shared with the load can cause significant errors. It is recommended to connect the sense resistor pads directly to the CSP and CSN

pins using “Kelvin” or “4-wire” connection techniques as shown below.



### Current Limit Setting

If output current hits current limit, output voltage drops to keep the current to a constant value.

The following equation calculates the constant current limit.

$$I_{Limit} (A) = \frac{66 mV}{R_{cs} (m\Omega)} \quad (6)$$

Where  $R_{cs}$  is current sense resistor.

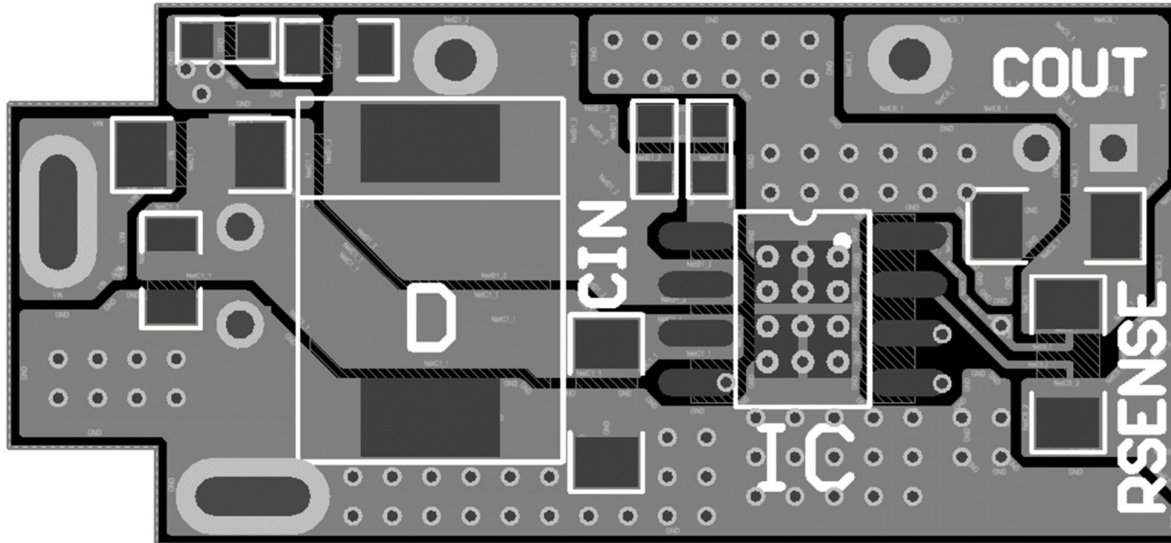
### PCB Layout Guidance

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the IC.

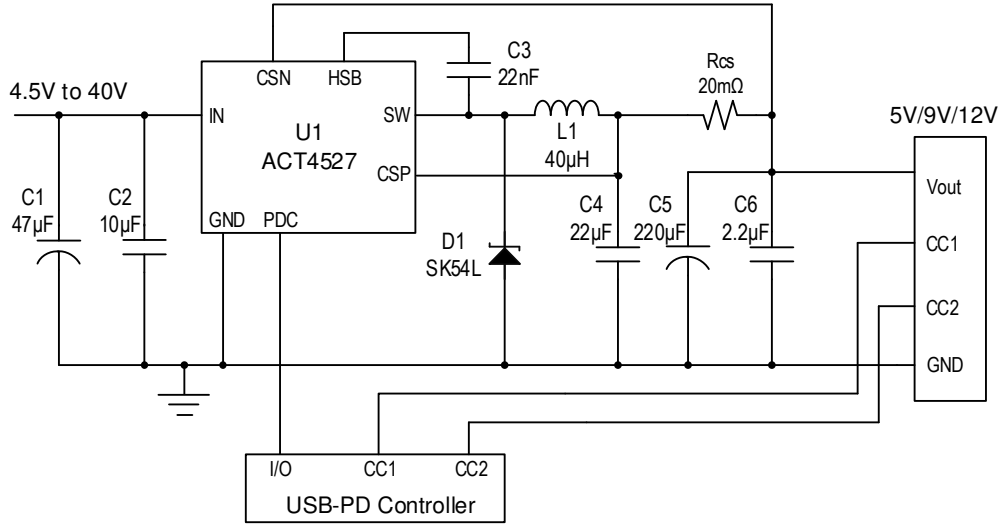
- 1) Arrange the power components to reduce the AC loop size consisting of  $C_{IN}$ ,  $V_{IN}$  pin, SW pin and the Schottky diode.
- 2) The high power loss components, e.g. the controller, Schottky diode, and the inductor should be placed carefully to make the thermal spread evenly on the board.
- 3) Place input decoupling ceramic capacitor  $C_{IN}$  as close to  $V_{IN}$  pin as possible.  $C_{IN}$  should be connected to power GND with several vias or short and wide copper trace.
- 4) Schottky anode pad and IC exposed pad should be placed close to ground clips in CLA applications.
- 5) Use “Kelvin” or “4-wire” connection techniques from the sense resistor pads directly to the CSP and CSN pins. The CSP and CSN traces should be in parallel to avoid interference.
- 6) Place multiple vias between top and bottom GND planes for best heat dissipation and noise immunity.
- 7) Use short traces connecting HSB- $C_{HSB}$ -SW loop.
- 8) SW pad is noise node switching from  $V_{IN}$  to GND. It should be isolated away from the rest of circuit for good EMI and low noise operation.



Example PCB Layout



**Typical Application Circuit**

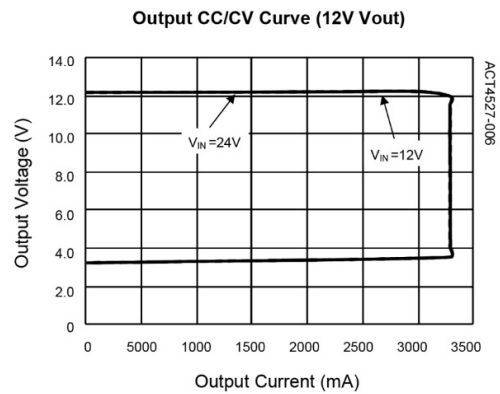
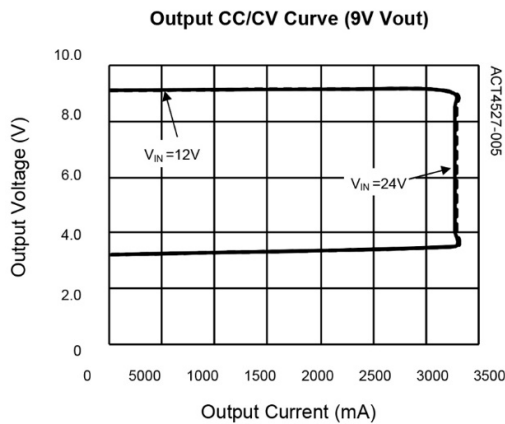
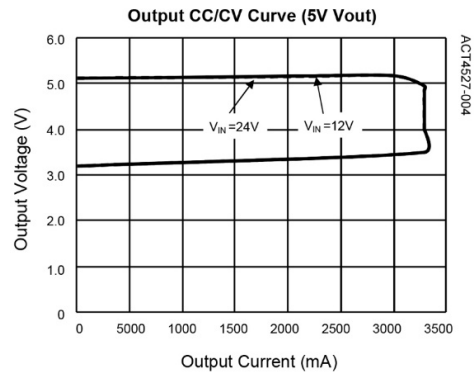
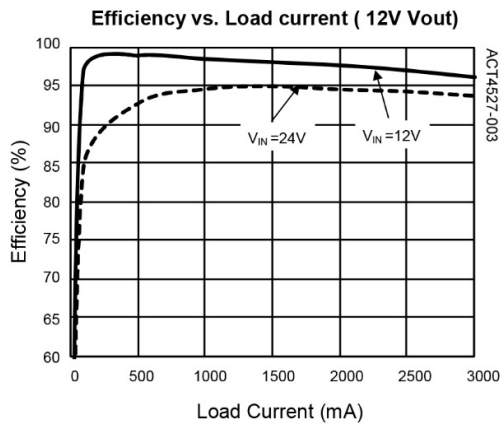
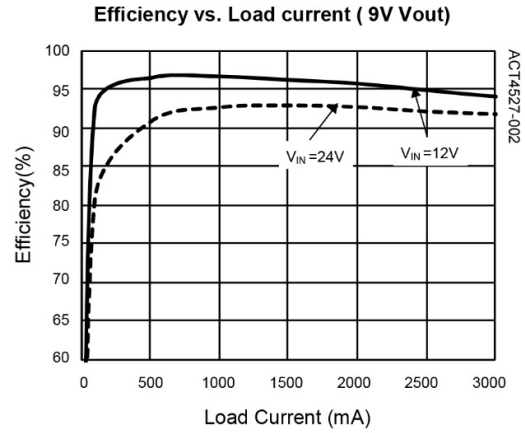
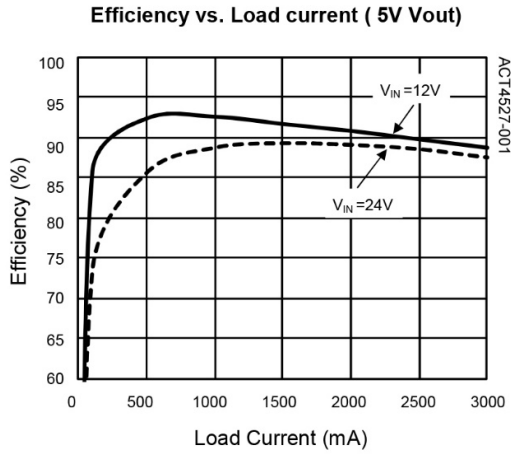


**BOM List for 3.0A USB PD Car Charger**

| ITEM | REFERENCE | DESCRIPTION                              | MANUFACTURER | QTY |
|------|-----------|--|--------------|-----|
| 1    | U1        | IC, ACT4527, SOP-8EP                     | Active-Semi  | 1   |
| 2    | C1        | Capacitor, Electrolytic, 47µF/35V        | Murata, TDK  | 1   |
| 3    | C2        | Capacitor, Ceramic, 10µF/25V, 1206, SMD  | Murata, TDK  | 1   |
| 4    | C3        | Capacitor, Ceramic, 22nF/25V, 0603, SMD  | Murata, TDK  | 1   |
| 5    | C4        | Capacitor, Ceramic, 22µF/16V, 1206, SMD  | Murata, TDK  | 1   |
| 6    | C5        | Capacitor, Electrolytic, 220µF/16V       | Murata, TDK  | 1   |
| 7    | C6        | Capacitor, Ceramic, 2.2µF/16V, 0805, SMD | Murata, TDK  | 1   |
| 8    | L1        | Inductor, 40µH, 4.0A, 20%                |              | 1   |
| 9    | D1        | Diode, Schottky, 40V/5A, SK54L           | Panjit       | 1   |
| 10   | Rcs       | Chip Resistor, 25mΩ, 1206, 1%            | Murata, TDK  | 1   |

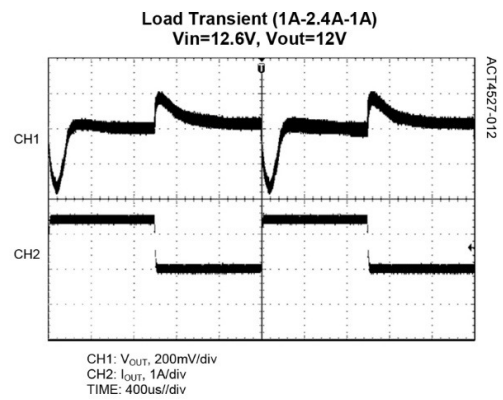
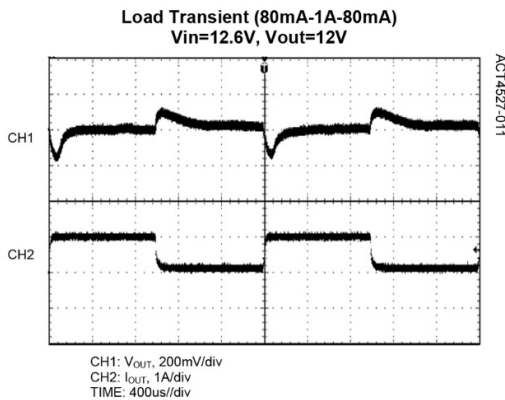
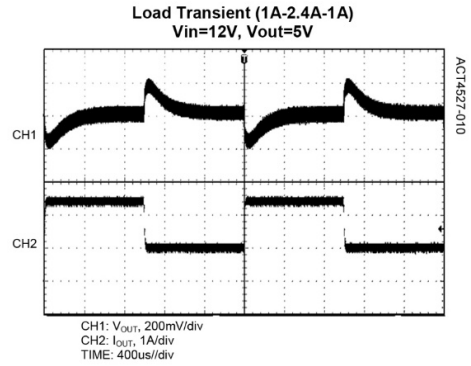
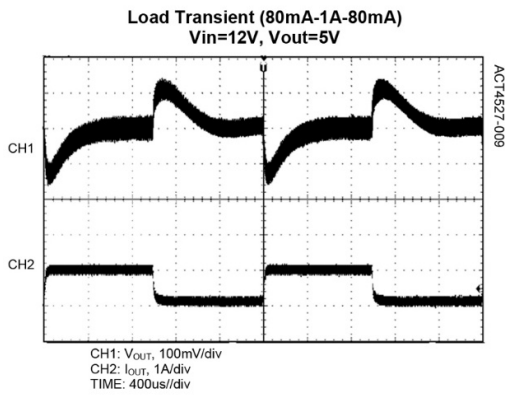
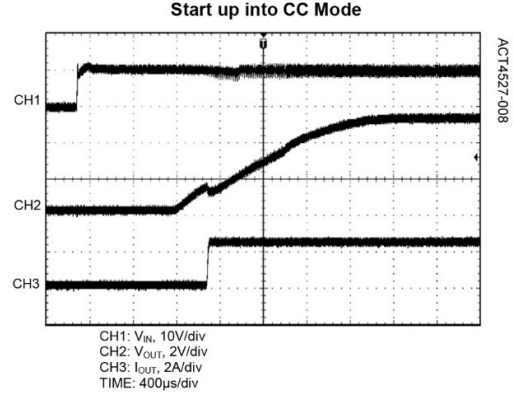
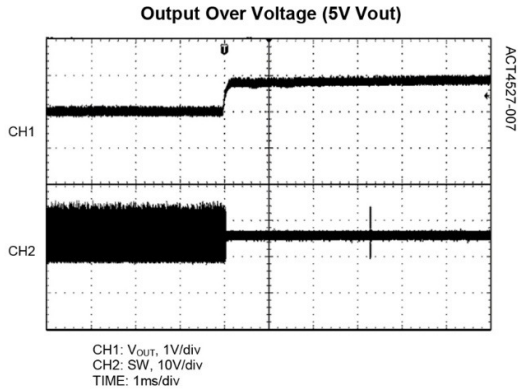
TYPICAL PERFORMANCE CHARACTERISTICS

(Schematic as shown in typical application circuit,  $T_a = 25^\circ\text{C}$ , unless otherwise specified)



TYPICAL PERFORMANCE CHARACTERISTICS

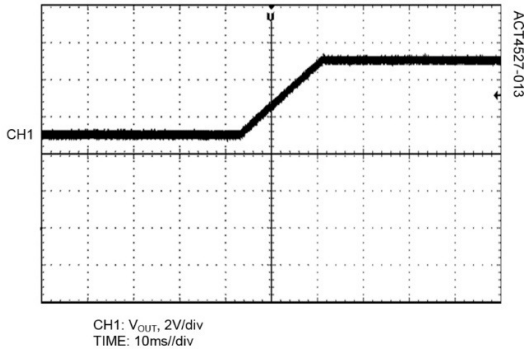
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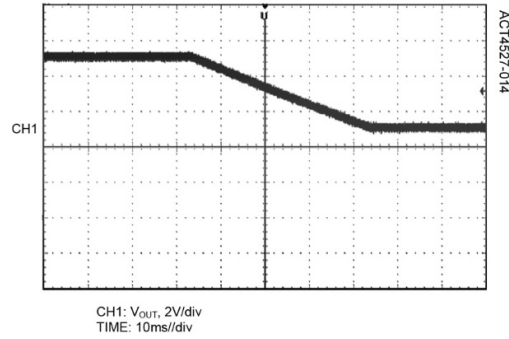
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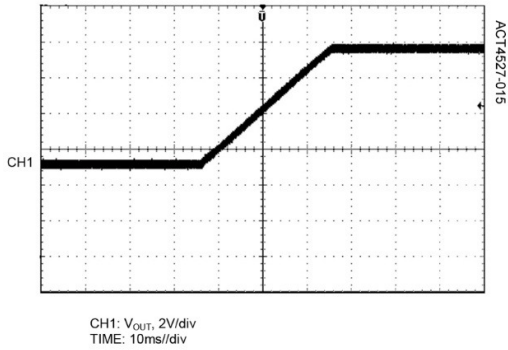
Voltage Transient (5V-9V)



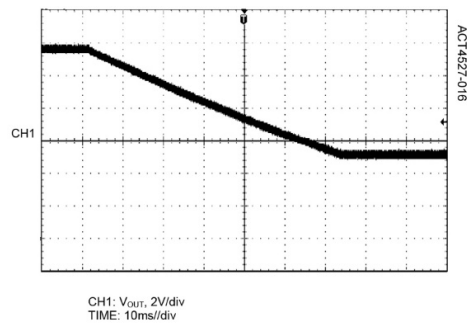
Voltage Transient (9V-5V)



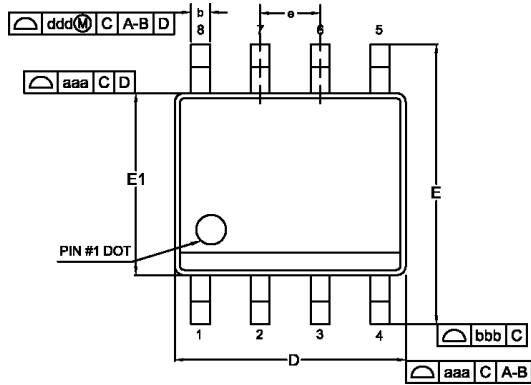
Voltage Transient (5V-12V)



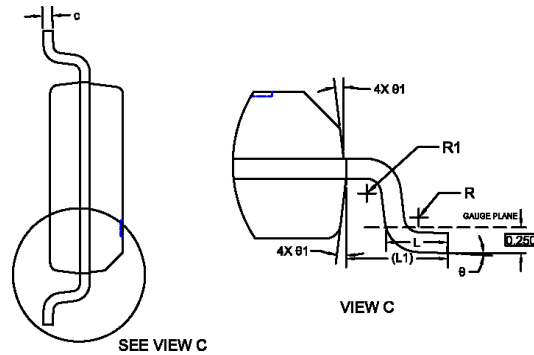
Voltage Transient (12V-5V)



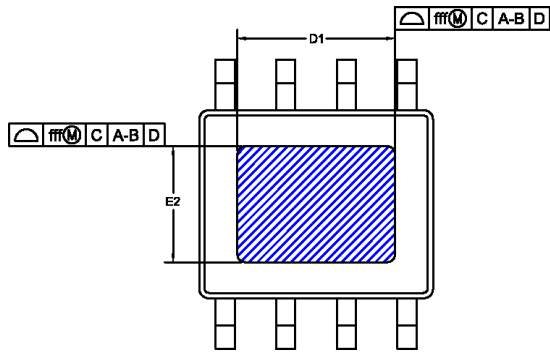
PACKAGE OUTLINE AND DIMENSIONS



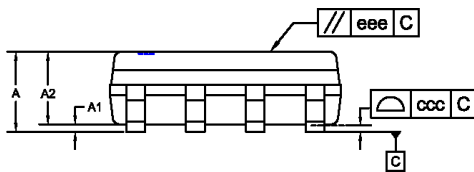
Top View



Side View



Bottom View



Side View

| Dimensional Ref.      |           |      |       |
|-----------------------|-----------|------|-------|
| REF.                  | Min.      | Nom. | Max.  |
| A                     | 1.370     | --   | 1.730 |
| A1                    | 0.025     | --   | 0.150 |
| A2                    | 1.250     | --   | --    |
| b                     | 0.360     | --   | 0.480 |
| c                     | 0.170     | --   | 0.250 |
| D                     | 4.900BSC  |      |       |
| E                     | 6.000BSC  |      |       |
| E1                    | 3.900BSC  |      |       |
| D1                    | 3.300BSC  |      |       |
| E2                    | 2.400BSC  |      |       |
| e                     | 1.270 BSC |      |       |
| L                     | 0.500     | --   | 1.000 |
| L1                    | 1.040REF. |      |       |
| R                     | 0.070     | --   | --    |
| R1                    | 0.070     | --   | --    |
| theta                 | 0°        | --   | 8°    |
| theta1                | 5°        | --   | 15°   |
| Tol. of Form&Position |           |      |       |
| aaa                   | 0.10      |      |       |
| bbb                   | 0.20      |      |       |
| ccc                   | 0.10      |      |       |
| ddd                   | 0.25      |      |       |
| eee                   | 0.10      |      |       |
| fff                   | 0.15      |      |       |

Notes

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5-2009.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. UNILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

## Product Compliance

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This part complies with RoHS directive 2011/65/EU as amended by (EU) 2015/863.

This part also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)



## Contact Information

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For the latest specifications, additional product information, worldwide sales and distribution locations:

**Web:** [www.qorvo.com](http://www.qorvo.com)

**Tel:** 1-844-890-8163

**Email:** [customer.support@qorvo.com](mailto:customer.support@qorvo.com)

For technical questions and application information:

**Email:** [appsupport@qorvo.com](mailto:appsupport@qorvo.com)

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